

## **ABSTRACT OF THE DISCLOSURE**

A thermal enhance MCM package mainly comprises a first chip, a second chip, a substrate and a thermally conductive device. The first chip and the second chip are electrically connected to the substrate, and the thermally conductive device is mounted on the substrate. The thermally conductive device is exposed to the outside so as to prevent the heat generated from the first chip and the second chip from being accumulated in the substrate and transmitted to the motherboard. Accordingly, the thermal performance of the MCM package will be upgraded.